

REMARKS

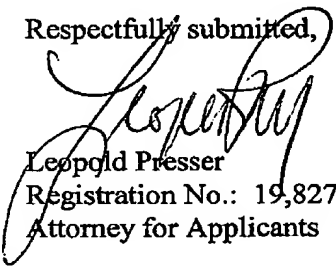
Applicants herewith submit new Claims 13 and 14 for the Examiner's consideration, noting that these clearly and unambiguously distinguish over the previously cited prior art, cited during the prosecution of this application, in effect, Japanese Patent Publication No. 11-107112.

In particular, applicants note that although the Japanese Publication discloses a support structure, such as for an integrated circuit package, and particularly a pad, there is no mention of the particular specific spacing between the strands of the mesh, which would support a circuitry pad which is arranged on a substrate. In particular, the dimensional aspects provided for by the present invention, as set forth in the new claims submitted herein, pertain to optimized values in making the sizes and thicknesses of the substrate and defining the spacings between the various strands so as to be able to effect a maximum degree of laminate support for the wire-bonded circuit device at a minimum amount of weight and physical displacement. The Japanese publication does not in any manner show optimized values analogous to those presented and claimed herein, but merely sets forth a generalized discussion relative to the spacing of fibers in a weave in order to form a fabric possessed of a desired strength. This has nothing in common with the particular clearly defined spacings, as set forth and claimed herein, nor of strand/weave dimensions and parameters, and a reading of the Japanese publication fails to provide any kind of teaching to one skilled in the art as to spacings and related criteria which would be optimized. To the contrary, the Japanese publication would necessitate the implementations of undue experimentation in order to be able to determine suitable diameter sizes for the strands of the weave and also the spacings between the adjacent strands, whereas the present disclosure and claims presented herein clearly and unambiguously set forth the actual optimized values and ranges, which are suitable for the particular type of physical application, namely, to provide a unique and highly advantageous laminate support in a wire-bonded

circuit device. Consequently, although the Japanese publication, to some extent, broadly discloses a mesh for a fabric, the latter of which is employed as a support structure, there is no teaching, nor even any suggestion in the prior art, as to the optimized values, in contrast with those specifically set forth herein. Accordingly, one skilled in the art would not be readily able to derive the present invention and the unique values provided therein by a reading of the Japanese publication, without having to involve extensive experimental procedures.

In view of the foregoing comments, the supportive arguments and the claims, as presented herein for the Examiner's consideration, in setting forth the specific optimized values, in contrast with the generalized disclosure in the Japanese publication, are deemed to be unambiguously directed to clearly allowable and patentable subject matter, and the early and favorable reconsideration of the application on the merits and issuance of the Notice of Allowance by the Examiner, is earnestly solicited. However, in the event that the Examiner has any queries concerning the instantly submitted Amendment, applicants' attorney respectfully requests that he be accorded the courtesy of possibly a telephone conference to discuss any matters in need of attention.

Respectfully submitted,


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Enclosure: Request for Continued Examination (RCE)